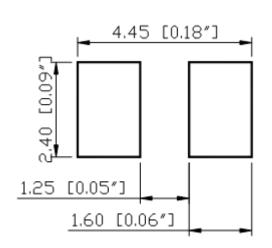


SPECIFICATION CSP1311R41C

PACKAGE OUTLINES 1.290 [0.11] 1.90 [0.07] 1.29 1.29 1.29 Re



ITEM	MATERIAL		
Resin	Silicon		
Lens Color	Water Transparent		
Dice	AlGaInP/GaAs		
Emitted Color	Red		

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number Chip Material		Color of Emission	Lens Type	Viewing Angle		
CSP1311R41C	InGaAlP	Red	Water Clear	120°		





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	5	μΑ	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for	5 sec Max	

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Symbol	Test Condition	Value			Lloit
			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	125	230	-	mcd
Forward Voltage	VF	IF = 20mA	ı	2.0	2.5	V
Reverse Leakage Current	lR	VR = 5V	1	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 10mA	ı	120	-	Deg
Peak Wavelength	λР	IF = 20mA	1	630	ı	nm
Dominant Wavelength	λD	IF = 20mA	615	620	630	nm

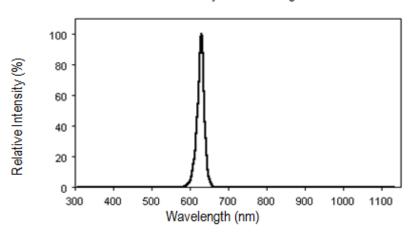
^{*}Tolerance of viewing angle: -10 / +5 deg.



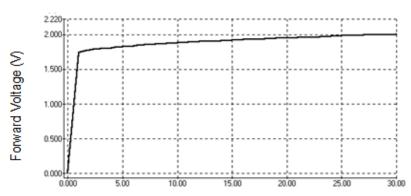


OPTICAL CHARACTERISTIC CURVES

Relative Intensity vs. Wavelength

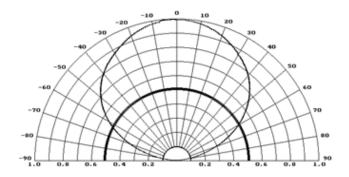


Forward Current vs. Forward Voltage



Forward Current (mA)

Directive Characteristics

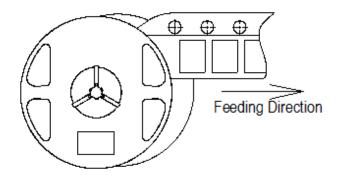




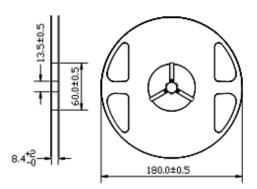


PACKAGING SPECIFICATION

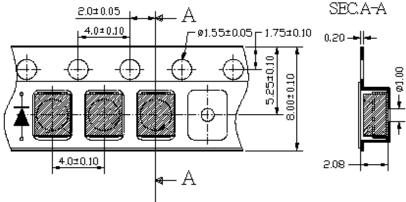
Feeding Direction



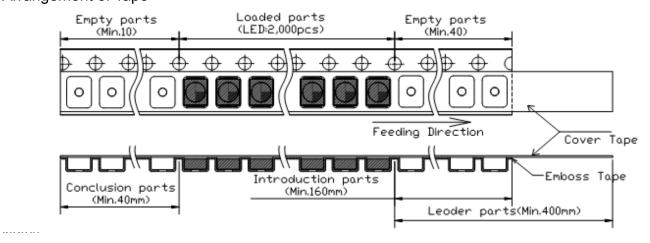
Dimensions of Reel (unit: mm)



Dimensions of Tape (unit: mm)



Arrangement of Tape



Notes:

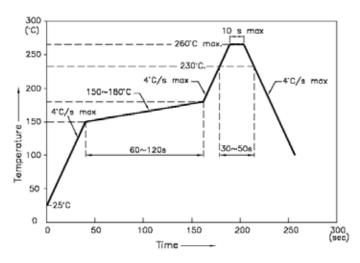
- 1. Empty component pockets are sealed with top cover tape
- 2. The maximum number of missing lamps is two.
- 3. 2000 pcs/reel





SOLDERING CONDITIONS

REFLOW PROFILE



Notes:

- 1. We recommend the reflow temperature 245°C (±5°C).the maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Soldering iron

- Basic spec is ≤ 5sec when 260°C. If temperature is higher, time should be shorter
- (+10°C → -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C.

Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil
- 3. Twin-head type is preferred.

